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11-1701

Staris

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): IWASAKI, et al.  
Serial No.: 09/255,856  
Filed: February 23, 1999  
For: SEMICONDUCTOR DEVICE WITH LAYERED  
INTERCONNECT STRUCTURE  
Group: 2813  
Examiner: S. Smoot

TECHNICAL STAFF  
11/13/2001  
[Signature]

AMENDMENT

Assistant Commissioner for Patents  
Washington, D.C. 20231

November 6, 2001

Sir:

In response to the Office Action mailed July 6, 2001, please amend the  
above-identified application as follows:

IN THE CLAIMS

Please amend the claims presently in the application as follows:

1. (Twice Amended) A semiconductor device with a multilayered  
structure comprising a copper film interconnect formed on one primary surface  
of a semiconductor substrate, and a neighboring film formed in contact with said